

Surface Mount Schottky Barrier Rectifier

FEATURES:

- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- Low power loss, high efficiency
- High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications

Circuit Diagram & Pin Configuration:



SOD-123FL

Marking

Type number	Marking code
DSS12	K12
DSS14	K14
DSS16	K16
DSS18	K18
DSS110	K110
DSS112	K112
DSS115	K115
DSS120	K120

Absolute Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz resistive or inductive load, for capacitive load, derate by 20 %

Parameter	Symbols	DSS12	DSS14	DSS16	DSS18	DSS110	DSS112	DSS115	DSS120	Units
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	20	40	60	80	100	120	150	200	V
Maximum RMS voltage	V _{RMS}	14	28	42	56	70	84	105	140	V
Maximum DC Blocking Voltage	V _{DC}	20	40	60	80	100	120	150	200	V
Maximum Average Forward Rectified Current	I _{F(AV)}	1.0								A
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I _{FSM}	25								A
Max Instantaneous Forward Voltage at 1 A	V _F	0.55		0.70		0.85		0.90		V
Maximum DC Reverse Current T _a = 25°C at Rated DC Reverse Voltage T _a =100°C	I _R	0.3 10				0.2 5		0.1 2		mA
Typical Junction Capacitance ⁽¹⁾	C _j	110		80						pF
Typical Thermal Resistance ⁽²⁾	R _{θJA}	100								°C/W
Operating Junction Temperature Range	T _j	-55 ~ +150								°C
Storage Temperature Range	T _{stg}	-55 ~ +150								°C

(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C

(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

Fig.1 Forward Current Derating Curve

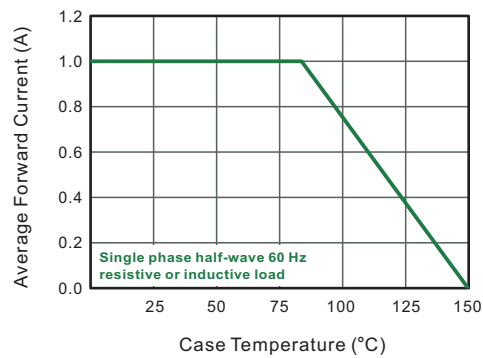


Fig.2 Typical Reverse Characteristics

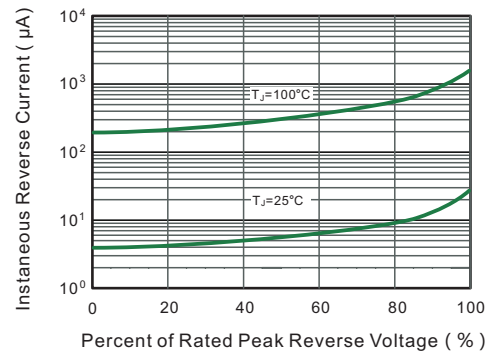


Fig.3 Typical Forward Characteristic

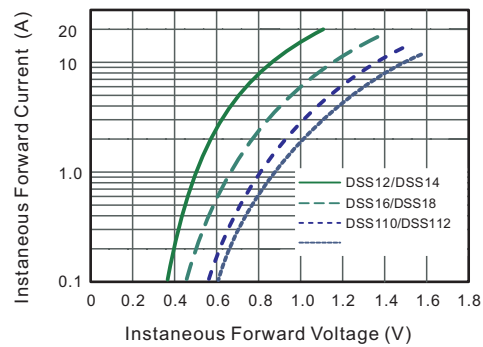


Fig.4 Typical Junction Capacitance

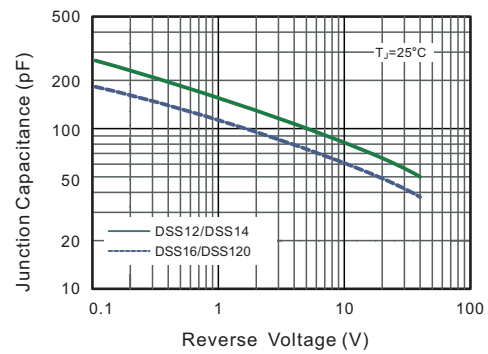


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

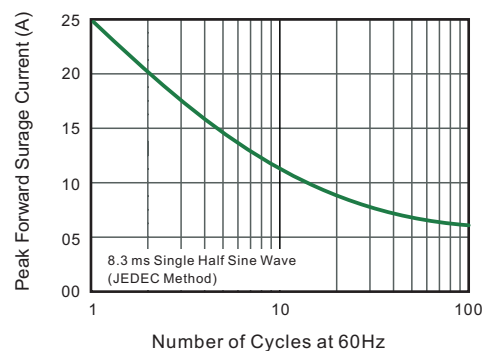
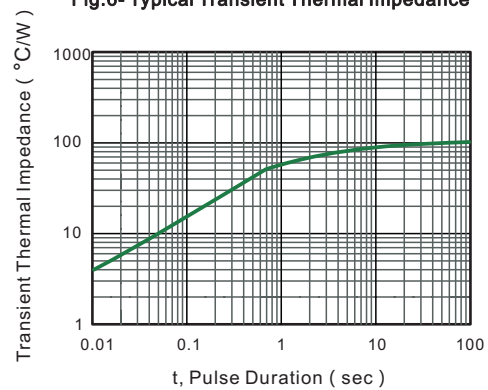


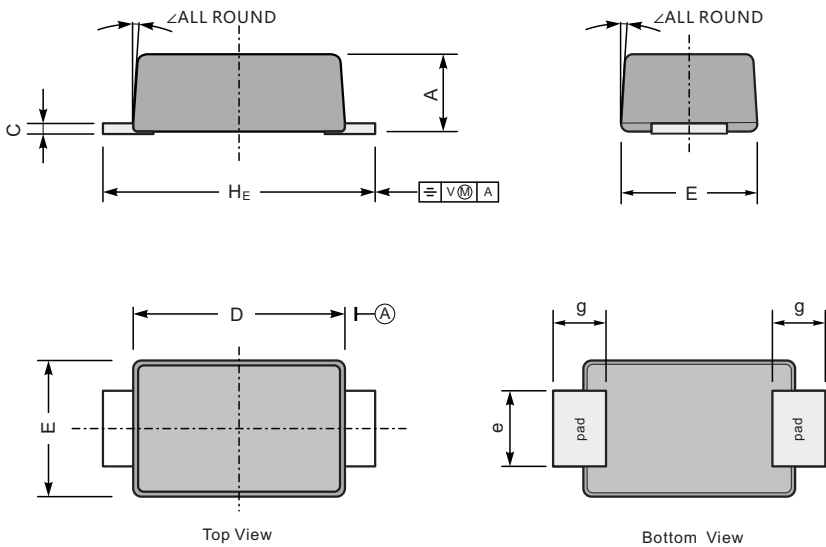
Fig.6- Typical Transient Thermal Impedance



PACKAGE OUTLINE

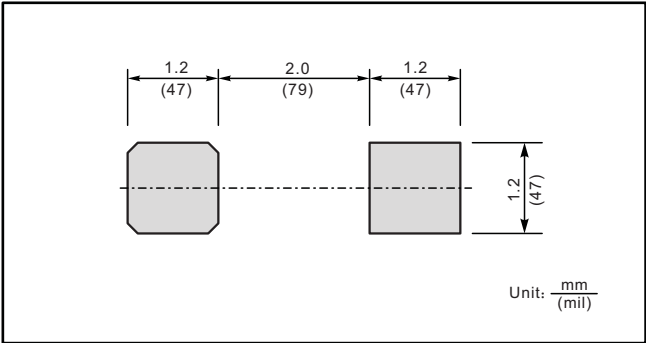
Plastic surface mounted package; 2 leads

SOD-123FL



UNIT		A	C	D	E	e	g	H _E	∠
mm	max	1.1	0.20	2.9	1.9	1.1	0.9	3.8	7°
	min	0.9	0.12	2.6	1.7	0.8	0.7	3.5	
mil	max	43	7.9	114	75	43	35	150	
	min	35	4.7	102	67	31	28	138	

The recommended mounting pad size



NOTICE

The information presented in this document is for reference only. Tinysemi reserves the right to make changes without notice for the specification of the products displayed herein.

The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or devices which require high level of reliability and the malfunction of which would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices), Tinysemi elec Co., Ltd., or anyone on its behalf, assumes no responsibility or liability for any damages resulting from such improper use of sale.

This publication supersedes & replaces all information previously supplied. For additional information, please visit our website <http://www.tinysemi.com>, or consult your nearest Tinysemi's sales office for further assistance.